MITSUBISHI ELECTRIC CORPORATION

No. KKZ0472-007

Dec. 9, 2007

Declaration of Conformity

We,

Manufacturer: Mitsubishi Electric Corporation, Fukuyama Works
Address: 1-8 Midorimachi, Fukuyama-city, Hiroshima, 720 Japan

declare our sole responsibility that the product

Description: Low-voltage Circuit-breakers
Models: indicated below including all accessories, marked with "<G>" to their packing cases

Air Circuit Breakers
AE630-SW, AE1000-SW, AE1250-SW, AE1600-SW, AE2000-SWA, AE2000-SW, AE2500-SW, AE3200-SW, AE4000-SWA, AE4000-SW, AE5000-SW, AE6300-SW

Molded-case Circuit Breakers
NF30-CS, NF63-CW, NF125-CW, NF250-CW, NF400-CW, NF630-CW, NF800-CEW, NF32-SW, NF63-SW, NF125-SW, NF125-SGW, NF160-SW, NF160-SGW, NF250-SW, NF250-SGW, NF400-SW, NF400-SEW, NF630-SW, NF630-SEW, NF800-SEW, NF1000-SEW, NF1250-SEW, NF1600-SEW, NF63-HW, NF125-HW, NF125-HGW, NF160-HW, NF160-HGW, NF250-HW, NF250-HGW, NF400-HEW, NF630-HEW, NF800-HEW, NF125-RW, NF125-UW, NF125-RGW, NF125-UGW, NF250-RW, NF250-UW , NF250-RGW, NF250-UGW, NF400-REW, NF400-UEW, NF630-REW, NF800-REW, NF800-UEW, NF800-SDW, NF1250-SDW, NF1600-SDW

Earth-leakage Circuit Breakers
NV30-CS, NV63-CW, NV125-CW, NV250-CW, NV400-CW, NV630-CW, NV32-SW, NV63-SW, NV125-SW, NV250-SW, NV250-SEW, NV400-SW, NV400-SEW, NV630-SW, NV630-SEW, NV800-SEW, NV63-HW, NV125-HW, NV125-RW, NV250-HW, NV250-HEW, NV250-RW, NV400-HEW, NV400-REW, NV630-HEW, NV800-HEW

Molded-Case Circuit Breaker With earth leakage current alarm
NF63-ZCW, NF125-ZCW, NF250-ZCW, NF400-ZCW, NF630-ZCW, NF63-ZSW, NF125-ZSW, NF250-ZSW, NF400-ZSW, NF630-ZSW, NF400-ZEW, NF630-ZEW, NF800-ZEW, NF63-ZHW, NF125-ZHW, NF250-ZHW

Motor-Protection Breakers
MB30-CS, MB30-SW, MB50-CW, MB50-SW, MB100-SW, MB225-SW

UL Listed Products
NF30-KC, NV30-KC, NF50-KC, NV50-KC, NF60-KC, NV60-KC, NV60-KCM, NV100-KC
NF30-FAU, NV30-FAU, NF50-FAU, NV50-FAU, NF50-SRU, NV50-SRU, NF50-SWU, NV50-SWU, NF50-FHU, NV50-FHU, NF100-CWU, NF100-SWU, NV100-SWU, NF100-SRU, NV100-SRU, NF100-FHU, NV100-FHU, NF100-HRU, NV100-HRU, NF225-SWU, NV225-SWU, NF-SFW, NF-SJW, NF-HJW, NF-SKW, NF-SLW

Circuit Protectors Type CP
CP30-BA, CP-S

Miniature Circuit Breakers
BH, BH-P, BH-S, BH-PS, BH-D6, BV-DN, BV-D, BV-DN, KB-D

to which this declaration relates is in conformity with the **Directive 2002/95/EC** on the restriction of the use of certain hazardous substances in electrical and electronic equipment.
This declaration certifies the conformity with the directives mentioned, but does not contain any warranted qualities.

Signature of representative for the manufacturer:

KAZUHIRO ISHII K. Oshii

Manager
Low voltage circuit breaker Planning Section
Low voltage circuit breaker Dept., Fukuyama Works

Information about RoHS

1. DIRECTIVE 2002/95/EC

Member States shall ensure that, from 1 July 2006, new electrical and electronic equipment put on the market does not contain lead, mercury, cadmium, hexavalent chromium, polybrominated biphenyls (PBB) or polybrominated diphenyl ethers (PBDE). National measures restricting or prohibiting the use of these substances in electrical and electronic equipment which were adopted in line with Community legislation before the adoption of this Directive may be maintained until 1 July 2006.

2. THRESHOLD LEVEL

For the purposes of the Directive, a maximum concentration value of 0.1 % by weight in homogeneous materials for lead, mercury, hexavalent chromium, polybrominated biphenyls (PBB) and polybrominated diphenyl ethers (PBDE) and of 0.01 % by weight in homogeneous materials for cadmium shall be tolerated.

3. EXEMPTIONS

Applications of lead, mercury, cadmium, hexavalent chromium, polybrominated biphenyls (PBB) or polybrominated diphenyl ethers (PBDE) which are exempted from the requirements of Article 4(1)

1. Mercury in compact fluorescent lamps not exceeding 5 mg per lamp.
2. Mercury in straight fluorescent lamps for general purposes not exceeding:
   — halophosphate 10 mg
   — triphosphate with normal lifetime 5 mg
   — triphosphate with long lifetime 8 mg.
3. Mercury in straight fluorescent lamps for special purposes.
4. Mercury in other lamps not specifically mentioned in this Annex.
5. Lead in glass of cathode ray tubes, electronic components and fluorescent tubes.
6. Lead as an alloying element in steel containing up to 0,35 % lead by weight, aluminium containing up to 0,4 % lead by weight and as a copper alloy containing up to 4 % lead by weight.
7. — Lead in high melting temperature type solders (i.e. lead-based alloys containing 85 % by weight or more lead),
   — lead in solders for servers, storage and storage array systems, network infrastructure equipment for switching, signalling, transmission as well as network management for telecommunications,
   — lead in electronic ceramic parts (e.g. piezoelectronic devices).';
8. Cadmium and its compounds in electrical contacts and cadmium plating except for applications banned under Directive 91/338/EEC (*) amending Directive 76/769/EEC (**) relating to restrictions on the marketing and use of certain dangerous substances and preparations.
9. Hexavalent chromium as an anti-corrosion of the carbon steel cooling system in absorption refrigerators.

9a. DecaBDE in polymeric applications;'

9b. Lead in lead-bronze bearing shells and bushes'.

10. Within the procedure referred to in Article 7(2), the Commission shall evaluate the applications for:
    — Deca BDE,
    — mercury in straight fluorescent lamps for special purposes,
    — lead in solders for servers, storage and storage array systems, network infrastructure equipment for switching, signalling, transmission as well as network management for telecommunications (with a view to setting a specific time limit for this exemption), and
    — light bulbs, as a matter of priority in order to establish as soon as possible whether these items are to be amended accordingly.
11. Lead used in compliant pin connector systems.
12. Lead as a coating material for the thermal conduction module c-ring.
13. Lead and cadmium in optical and filter glass.
14. Lead in solders consisting of more than two elements for the connection between the pins and the package of microprocessors with a lead content of more than 80 % and less than 85 % by weight.
15. Lead in solders to complete a viable electrical connection between semiconductor die and carrier within integrated circuit Flip Chip packages.'
16. Lead in linear incandescent lamps with silicate coated tubes.
17. Lead halide as radiant agent in High Intensity Discharge (HID) lamps used for professional reprography applications.
18. Lead as activator in the fluorescent powder (1 % lead by weight or less) of discharge lamps when used as sun tanning lamps containing phosphors such as BSP (BaSi2O5:Pb) as well as when used as speciality lamps for diazo-printing reprography, lithography, insect traps, photochemical and curing processes containing phosphors such as SMS ((Sr,Ba)2MgSi2O7:Pb).
19. Lead with PbBiSn-Hg and PbInSn-Hg in specific compositions as main amalgam and with PbSn-Hg as auxiliary amalgam in very compact Energy Saving Lamps (ESL).
20. Lead oxide in glass used for bonding front and rear substrates of flat fluorescent lamps used for Liquid Crystal Displays (LCD).'